

NOTICE: This correspondence chart is provided for informational purposes only. It is not a part of the official Patent Application.

## CORRESPONDENCE CHART

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	10, 10A	INTEGRATED CAMERA MODULE
	12	CAMERA CHIP
	14	SENSOR ARRAY AREA
	16, 16A	PCB
10	17	ATTACHMENT WIRES
	18	PASSIVE COMPONENTS
	20	CONTACT PADS
	22, 22A	PCB ASSEMBLY
	24, 24A	LENS ASSEMBLY
15	26	MOLDING
	28	ADHESIVE
	29	RECESSED AREA (IN MOLDING 26)
	30	GAP
	32	Z DIMENSION
20	34	X DIMIMENSION
	36	Y DIMIMENSION
	38	APERTURE
	40	ATTACHMENT FINGERS
	44	FLEX CIRCUIT
25	46	EDGE CONNECTOR PADS
	48	FLEX CIRCUIT ASSEMBLY
	50	HOT BAR ATTACH POINT
	52	SUBSTRATE STRIP
	54	ALIGNMENT HOLES
30	56	MOLD CHASE
	58	MOLD INSERTS

	60	PROTECTIVE TAPE
	62	LENS HOUSING
	64	FIRST LENS
	66	SECOND LENS
5	70	ADHESIVE WELL
	100	CAMERA MODULE CONSTRUCTION METHOD
	110	SOLDER PASTE PRINT OPERATION
	112	PASSIVE ATTACH OPERATION
	114	REFLOW OPERATION
10	116	CLEANER OPERATION
	118	DIE BONDING OPERATION
	120	OVER MOLDING OPERATION
	122	PLASMA CLEANING OPERATION
	124	WIRE BONDING OPERATION
15	126	PLASMA CLEANING OPERATION
	128	OVER MOLDING OPERATION
	130	OVER MOLDING CURING OPERATION
	132	ATTACH COVER TAPE OPERATION
	134	SAW SINGULATION OPERATION
20	138	REMOVE COVER TAPE OPERATION
	140	LENS MOUNTING OPERATION
	142	FOCUS AND TESTING OPERATION
	144	GLUE DISPENSING AND CURING OPERATION
	146	PACKAGING OPERATION

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